

REMARKS/ARGUMENTS

The claims have been amended to point out preferred embodiments of the invention. The amendments to Claims 1, 4, 9 and 12 find support at, e.g., specification page 21, line 6 – page 22, line 9, and the paragraph bridging specification pages 25 and 26. New claims 28 and 32 place Claims 7 and 14 into independent form. As these claims are allowable (Examiner Rose is thanked for this indication of allowable subject matter), claims 28-34 are allowable. Other amendments are formal in nature. No new matter has been added.

The claims are patentable over Kuramochi '403 and Kuramochi '581.

Kuramochi '403 relates to a fired porous silica molding having a non-abrasive soluble material coated in the pores thereof. See, for example, col. 3, lines 9-17, col. 4, lines 30 – col. 5, line 13, col. 6, lines 19-22, and example 1 at col. 11, lines 6-18 of the reference. In Example 1, cited in the Official Action, the silica is fired in a furnace and then impregnated with a wax.

Thus, the reference does not disclose a polishing body or a polishing part with a predetermined shape comprising an abrasive dispersed in a matrix material. That is, even where the soluble solid is a polymeric resin in Kuramochi, it is the silica body that is the abrasive, and, at best, only a minor proportion of soluble solid is present inside the pores of the disclosed abrasive silica member. Accordingly, the Kuramochi material is essentially *opposite* that of the claims herein, which require an abrasive dispersed in a matrix material. As noted above, in Example 1 of Kuramochi the silica is fired in a furnace and then impregnated with a wax: the precursor spray-dried granules contain no other material, and would not be used on a polishing pad, or to polish semiconductors.

In addition, the abrasive material in Kuramochi '403 is not prepared by eliminating a dispersion medium from an aqueous dispersion comprising an abrasive dispersed in a matrix material. This difference in methodology leads to a different final structure altogether, as

noted above, and provides a distinction even as compared to a very similar process in which a *non*-aqueous dispersion medium is used: compare the results for invention polishing body A (made from an aqueous dispersion – pg. 21) with those for Comparative Example D (made with a non-aqueous dispersion – pg 25) in Table 4 at specification page 28. As noted at pages 28-29, non-aqueous D performed poorly, showing scratches, etc.

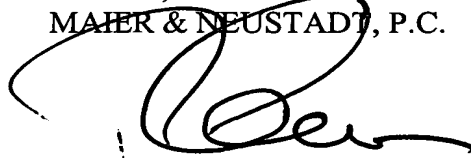
The situation is quite similar for Kuramochi '581. Example 4, cited in the Official Action, *sinters* the spray dried slurry at 950 °C for two hours, thus removing by heat (pyrolysis, etc.) the organic materials therein (acrylic binder, stearic acid) to provide an abrasive. The precursor disc contains very little acrylic binder and stearic acid (the silica/acrylic binder/stearic acid emulsion/water ratio is 100/17/1/251 by weight), and thus cannot be considered to describe an abrasive dispersed in a matrix material, as presently claimed. Certainly, the intermediate precursor disc would not be used on a polishing pad, or to polish semiconductors prior to the significant changes that occur on sintering.

Accordingly, and for the reasons discussed above and in view of the amendments to the claims, applicants submit that neither of the Kuramochi references disclose or suggest the invention as now claimed, and the rejections over these references should be withdrawn.

The claims are now in condition for allowance, and early notification thereof is respectfully requested.

Respectfully submitted,

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